

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TAKAHIRO SASAKI	08/29/2017
KENICHI TAKAHASHI	08/22/2017
HIROSHI OHGA	08/22/2017
TATSUYA FUKUGAKI	08/22/2017
SHIGERU YANO	08/22/2017
KENICHI YASUZAWA	08/22/2017
NOZOMI HASEGAWA	08/22/2017
MASAAKI HANAWA	08/23/2017
RECEIVING PARTY DATA	
Name:	HITACHI HIGH-TECHNOLOGIES CORPORATION
Street Address:	24-14, NISHI SHIMBASHI 1-CHOME, MINATO-KU
City:	TOKYO
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15664343
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	T&A-8573-02
NAME OF SUBMITTER:	SHRINATH MALUR
SIGNATURE:	/Shrinath Malur/
DATE SIGNED:	10/06/2017

PATENT

Total Attachments: 2

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ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI HIGH-TECHNOLOGIES CORPORATION, a corporation organized under the laws of Japan, located at 24-14, Nishi Shimbashi 1-chome, Minato-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI HIGH-TECHNOLOGIES CORPORATION, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SAMPLE TEST AUTOMATION SYSTEM

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said HITACHI HIGH-TECHNOLOGIES CORPORATION,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI HIGH-TECHNOLOGIES CORPORATION.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Takahiro Sasaki</u> (Takahiro SASAKI)	<u>8/29/2017</u>
2) _____ (Kenichi TAKAHASHI)	_____
3) _____ (Hiroshi OHGA)	_____
4) _____ (Tatsuya FUKUGAKI)	_____
5) _____ (Shigeru YANO)	_____
6) _____ (Kenichi YASUZAWA)	_____
7) _____ (Nozomi HASEGAWA)	_____
8) _____ (Masaaki HANAWA)	_____

ASSIGNMENT

(譲渡証)

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invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said HITACHI HIGH-TECHNOLOGIES CORPORATION, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI HIGH-TECHNOLOGIES CORPORATION.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) _____ (Takahiro SASAKI)	_____
2) <u>Kenichi Takahashi</u> (Kenichi TAKAHASHI)	<u>8/22/2017</u>
3) <u>Hiroshi OHGA</u> (Hiroshi OHGA)	<u>8/22/2017</u>
4) <u>Tatsuya Fukugaki</u> (Tatsuya FUKUGAKI)	<u>8/22/2017</u>
5) <u>Shigeru YANO</u> (Shigeru YANO)	<u>8/22/2017</u>
6) <u>Kenichi YASUZAWA</u> (Kenichi YASUZAWA)	<u>8/22/2017</u>
7) <u>Nozomi HASEGAWA</u> (Nozomi HASEGAWA)	<u>8/22/2017</u>
8) <u>Masaaki Hanawa</u> (Masaaki HANAWA)	<u>8/23/2017</u>

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RECORDED: 10/06/2017

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